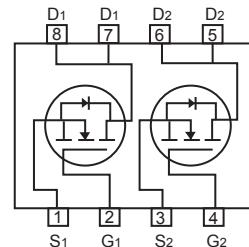
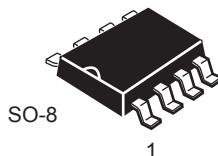


## Dual N-Channel Enhancement Mode Field Effect Transistor

## FEATURES

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- 30V, 9.1A,  $R_{DS(ON)} = 15m\Omega$  @ $V_{GS} = 10V$ .  
 $R_{DS(ON)} = 21m\Omega$  @ $V_{GS} = 4.5V$ .
- 30V, 6.9A,  $R_{DS(ON)} = 26m\Omega$  @ $V_{GS} = 10V$ .  
 $R_{DS(ON)} = 35m\Omega$  @ $V_{GS} = 4.5V$ .
- Super high dense cell design for extremely low  $R_{DS(ON)}$ .
- High power and current handing capability.
- Lead free product is acquired.
- Surface mount Package.

ABSOLUTE MAXIMUM RATINGS  $T_A = 25^\circ C$  unless otherwise noted

Parameter	Symbol	Channel 1	Channel 2	Units
Drain-Source Voltage	$V_{DS}$	30	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	$\pm 20$	V
Drain Current-Continuous	$I_D$	9.1	6.9	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM}$	36.4	27.6	A
Maximum Power Dissipation	$P_D$	2.0		W
Operating and Store Temperature Range	$T_J, T_{Stg}$	-55 to 150		°C

## Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Ambient <sup>b</sup>	$R_{\theta JA}$	62.5	°C/W

N-Channel(Q1) Electrical Characteristics  $T_A = 25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	30			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 24\text{V}, V_{\text{GS}} = 0\text{V}$			1	$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA
<b>On Characteristics</b> <sup>c</sup>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	1		3	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 8.6\text{A}$		12	15	$\text{m}\Omega$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}} = 5\text{V}, I_D = 8.6\text{A}$		17	21	$\text{m}\Omega$
<b>Dynamic Characteristics</b> <sup>d</sup>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		2110		pF
Output Capacitance	$C_{\text{oss}}$			400		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			260		pF
<b>Switching Characteristics</b> <sup>d</sup>						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 15\text{V}, I_D = 1\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega$		14	28	ns
Turn-On Rise Time	$t_r$			10	20	ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			46	92	ns
Turn-Off Fall Time	$t_f$			16	32	ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 15\text{V}, I_D = 12\text{A}, V_{\text{GS}} = 5\text{V}$		19.8	26.3	nC
Gate-Source Charge	$Q_{\text{gs}}$			6.4		nC
Gate-Drain Charge	$Q_{\text{gd}}$			5.8		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current <sup>b</sup>	$I_S$				3	A
Drain-Source Diode Forward Voltage <sup>c</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_S = 3\text{A}$			1.2	V

## Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature.□
- b.Surface Mounted on FR4 Board, t ≤ 10 sec.□
- c.Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.□
- d.Guaranteed by design, not subject to production testing.□



# CEM3138

## N-Channel(Q2) Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

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Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	30			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 24\text{V}, V_{\text{GS}} = 0\text{V}$		1		$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$		100		nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$		-100		nA
<b>On Characteristics<sup>c</sup></b>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	1		3	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 6.3\text{A}$		20	26	$\text{m}\Omega$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}} = 5\text{V}, I_D = 6.3\text{A}$		27	35	$\text{m}\Omega$
<b>Dynamic Characteristics<sup>d</sup></b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		862		pF
Output Capacitance	$C_{\text{oss}}$			464		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			146		pF
<b>Switching Characteristics<sup>d</sup></b>						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 15\text{V}, I_D = 1\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega$		15	30	ns
Turn-On Rise Time	$t_r$			11	25	ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			30	60	ns
Turn-Off Fall Time	$t_f$			16	32	ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 15\text{V}, I_D = 12\text{A}, V_{\text{GS}} = 5\text{V}$		12.7	16.5	nC
Gate-Source Charge	$Q_{\text{gs}}$			3.7		nC
Gate-Drain Charge	$Q_{\text{gd}}$			4.1		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current <sup>b</sup>	$I_S$				1.3	A
Drain-Source Diode Forward Voltage <sup>c</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_S = 1.3\text{A}$			1.2	V

Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature.□
- b.Surface Mounted on FR4 Board, t ≤ 10 sec.□
- c.Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.□
- d.Guaranteed by design, not subject to production testing.□

## CHANNEL 1

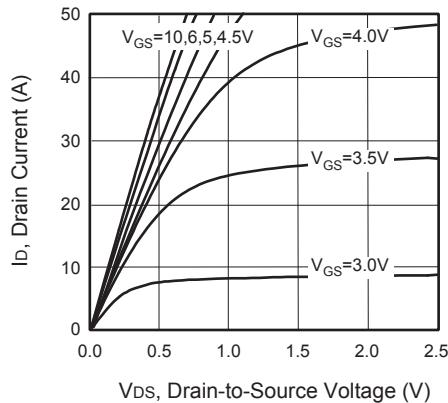
V<sub>DS</sub>, Drain-to-Source Voltage (V)

Figure 1. Output Characteristics

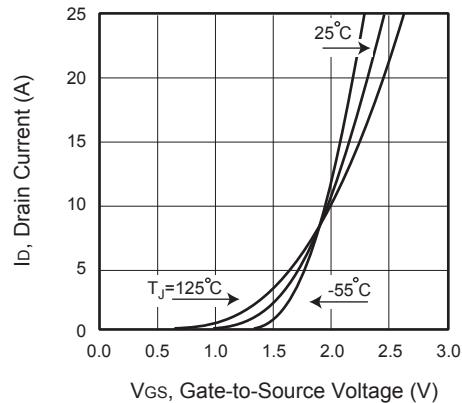
V<sub>GS</sub>, Gate-to-Source Voltage (V)

Figure 2. Transfer Characteristics

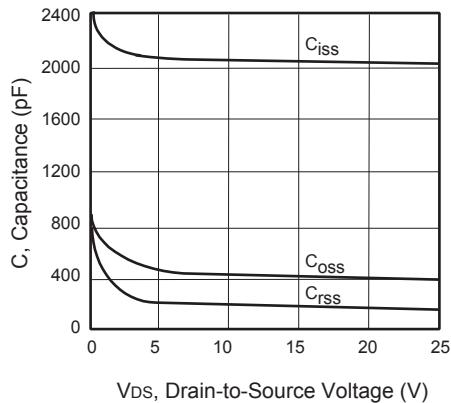
V<sub>DS</sub>, Drain-to-Source Voltage (V)

Figure 3. Capacitance

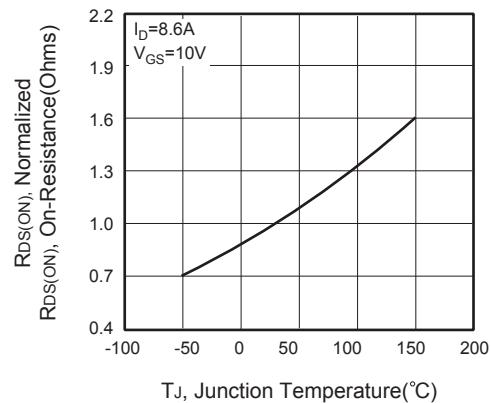
 $T_J$ , Junction Temperature (°C)

Figure 4. On-Resistance Variation with Temperature

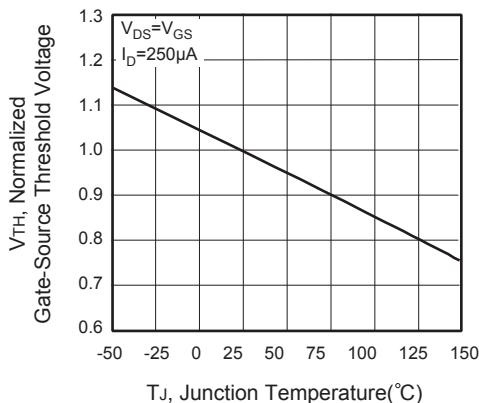
 $T_J$ , Junction Temperature (°C)

Figure 5. Gate Threshold Variation with Temperature

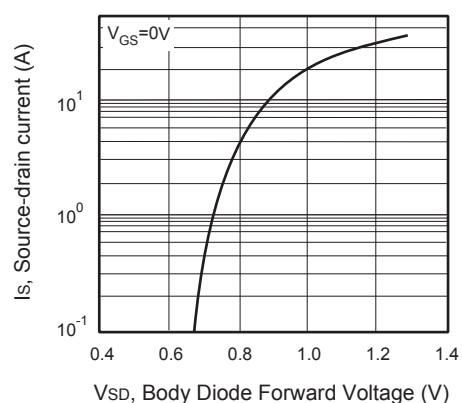
 $V_{SD}$ , Body Diode Forward Voltage (V)

Figure 6. Body Diode Forward Voltage Variation with Source Current

## CHANNEL 2

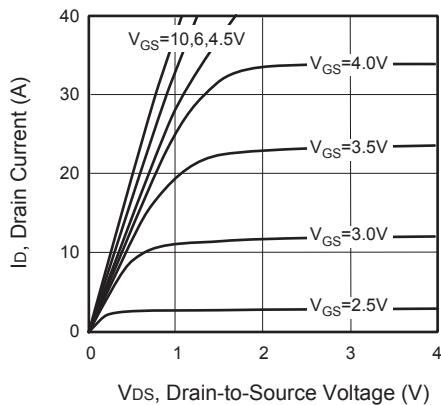


Figure 7. Output Characteristics

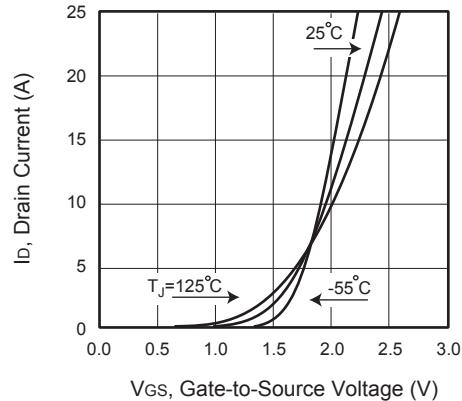


Figure 8. Transfer Characteristics

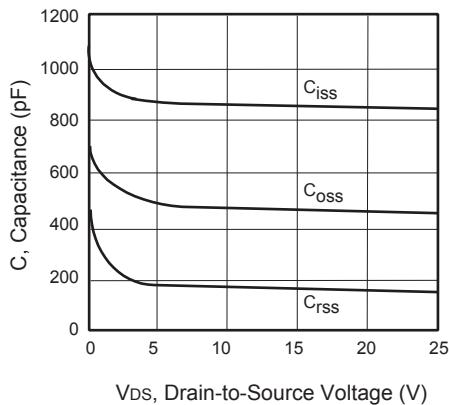


Figure 9. Capacitance

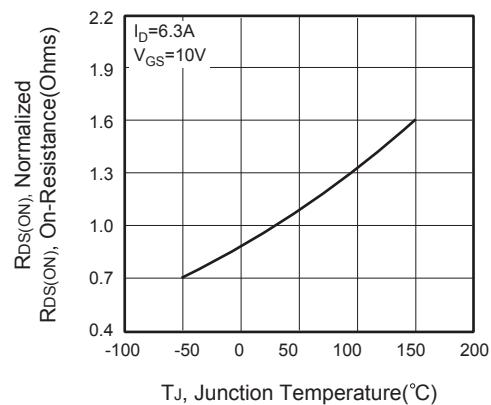


Figure 10. On-Resistance Variation with Temperature

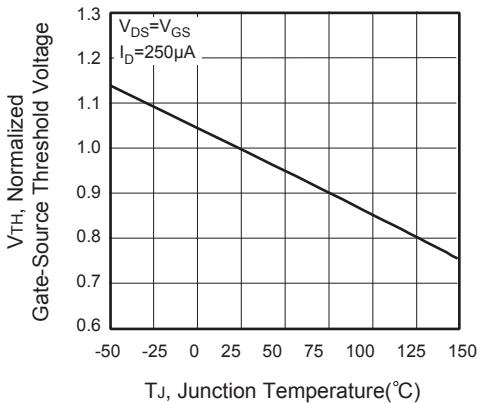


Figure 11. Gate Threshold Variation with Temperature

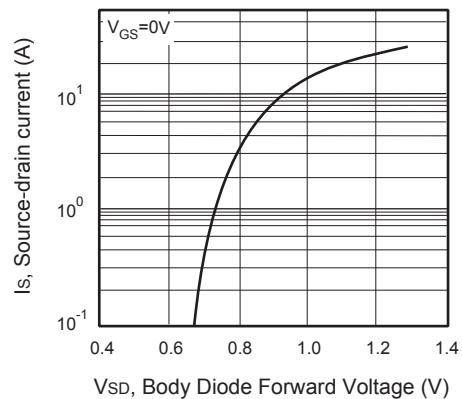
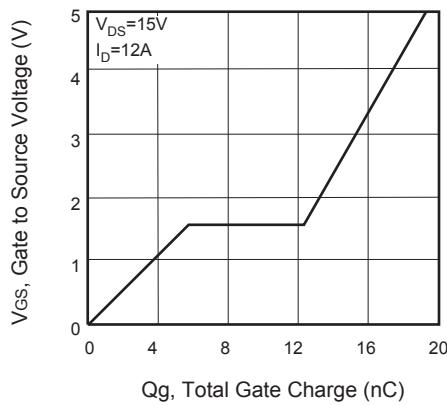
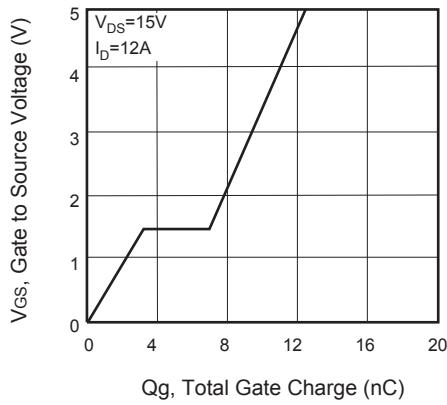
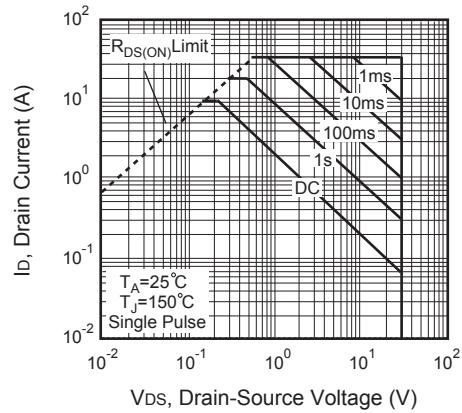
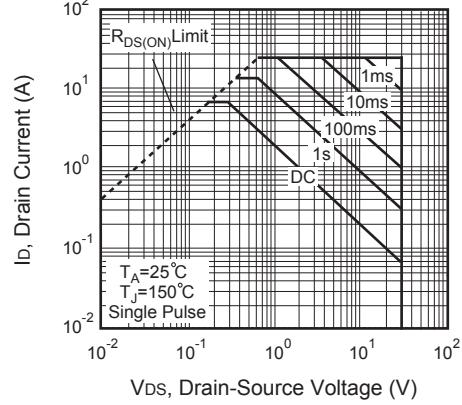
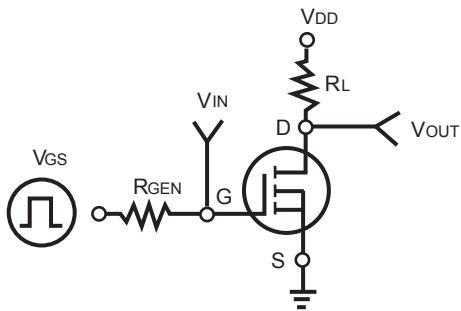
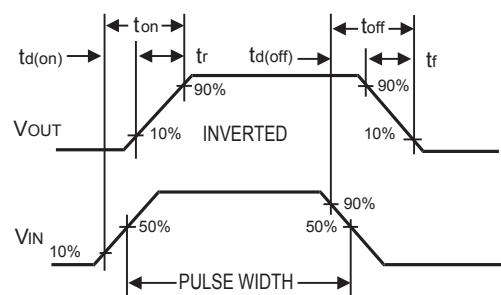


Figure 12. Body Diode Forward Voltage Variation with Source Current

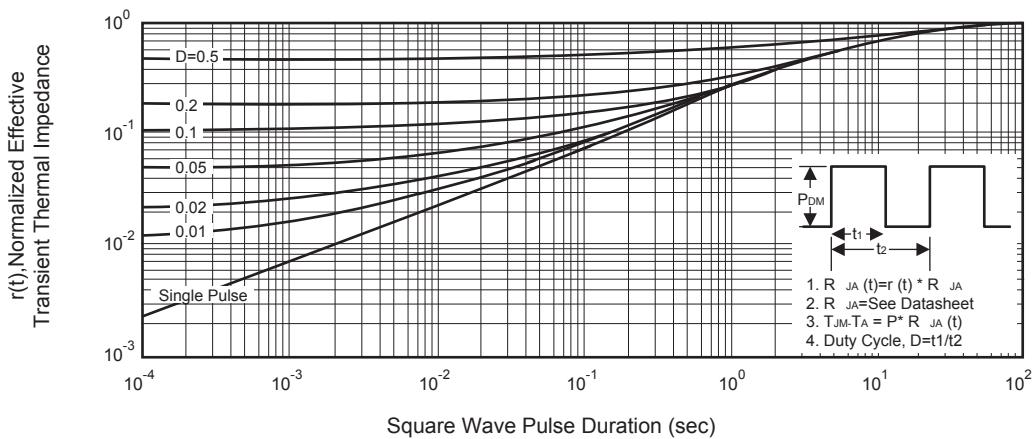
**CHANNEL 1****Figure 13. Gate Charge****CHANNEL 2****Figure 15. Gate Charge****Figure 14. Maximum Safe Operating Area****Figure 16. Maximum Safe Operating Area**



**Figure 17. Switching Test Circuit**



**Figure 18. Switching Waveforms**



**Figure 19. Normalized Thermal Transient Impedance Curve**